

Features :

- Isolated mounting base 3000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications :

- Inverter
- Inductive heating
- Chopper

V _{RSM}	V _{RRM}	品名
700V	600V	Mx400DF60
900V	800V	Mx400DF80
1100V	1000V	Mx400DF100
1300V	1200V	Mx400DF120
1500V	1400V	Mx400DF140
1700V	1600V	Mx400DF160
1900V	1800V	Mx400DF180

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _J (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =85°C	140			400	A
I _{F(RMS)}	RMS forward current					628	A
I _{RRM}	Repetitive peak current	at V _{RRM}	140			90	mA
I _{FSM}	Surge forward current	10ms half sine wave V _R =0.6V _{RRM}	140			9.5	kA
I ² t	I ² t for fusing coordination					451	10 ³ A ² s
V _{FO}	Threshold voltage		140			1.10	V
r _F	Forward slope resistance					0.27	mΩ
V _{FM}	Peak forward voltage	I _{FM} =1200A	25			2.00	V
t _{rr}	Reverse recovery time	I _{FM} =300A, t _p =4000μs, -di/dt=20A/μs, V _R =50V	140		4		μs
			25		3		μs
R _{th(j-c)}	Thermal resistance Junction to case	D.C. Single side cooled per chip				0.090	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	D.C. Single side cooled per chip				0.020	°C/W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I _{iso} :1mA(MAX)		3000			V
F _m	Terminal connection torque(M12)			12.0		14.0	N·m
	Mounting torque(M8)			10.0		12.0	N·m
T _{vj}	Junction temperature			-40		140	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				3310		g
Outline	M07						

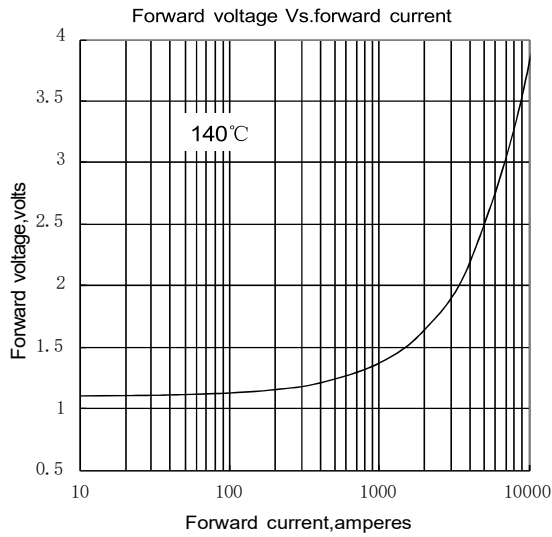


Fig.1

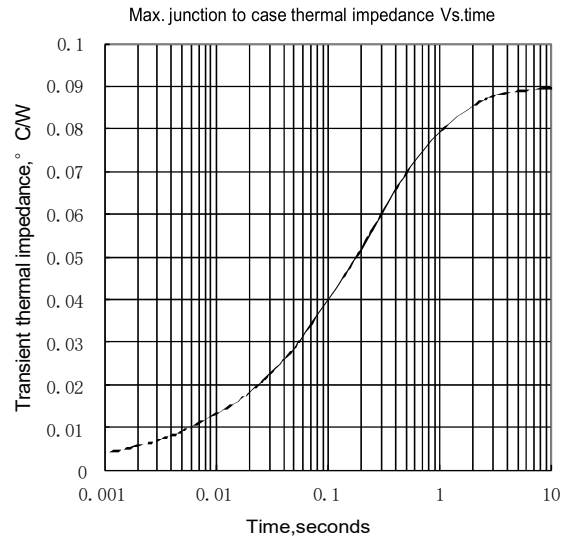


Fig.2

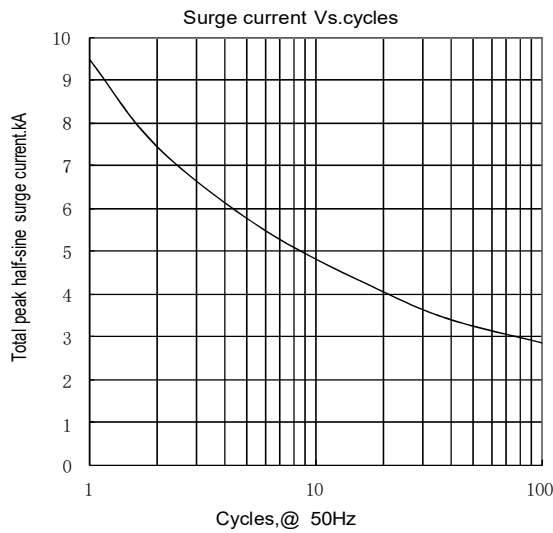
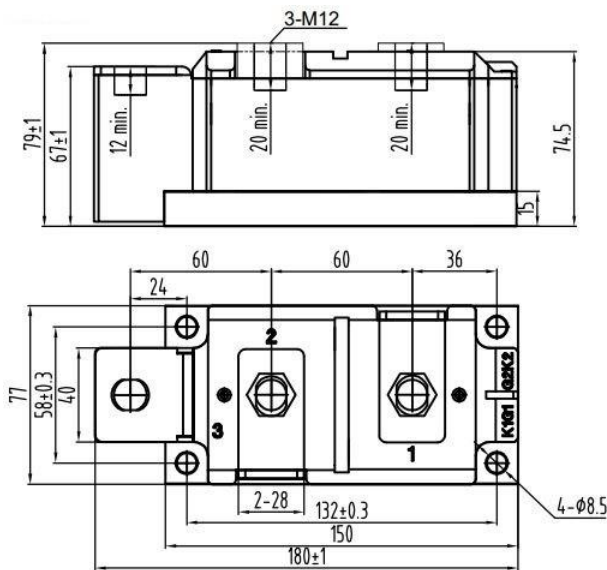


Fig.3

Outline:



Unmarked dimensional tolerance: ±0.5mm

NIPS reserves the right to change specifications without notice.

